Semiconductor & Microelectronic Assembly

www.npos-usa.com

Model JFP S200-6

6" WAFER SCRIBER



APPLICATIONS

- Thin Glass
- ❖ Borosilicate
- Silicon
- ❖ GaAs
- Alumina
- Sapphire

Scribe Model S200-6 is easy to use for singulating components till 6" wafer. Robust; vibration free the scribe S200-6 unit is immediately operational, with extremely friendly user interface. Vertical targeting is carried out with a video set including an electronic crosshair. A LCD screen allows parameters display and selected through programming wheel.

The S220-6 series provide customers with the highest quality and best cost / performance system on the market. Our proven expertise in scribing application effectively provides the technology and support to help our customers. Optional 8" wafer model also available.



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Specifications	
MODEL	Automatic Scriber S200-6
SCRIBING HEAD	 Z motion with adjustable angle Ajustable scribing force from 10gr up to 150gr / constant weight Diamond Tool: Adjustable for angle & rotation Tool Offset with cross-hair Accuracy: ±5µm
WAFER TABLE	 Wafer chuck till 6" Hold by vacuum Frame / Ring adaptator XY & Theta Motorized table Rotation & alignment by interpolation / Motorization X Y Table / resolution 1µm; Accuracy ±5µm Motion control with progressive joystick weight
VISION SYSTEM	 Field of view 1mm TFT monitor 17" CCD color camera high definition Target cross generator LED lightings
PARAMETERS	 Optics & magnification compatible with application Step Index Y scribe speed from 1 to 100mm/sec Scribing length programmable Repeat scribe Number of scribe Step Index Multi index capability Cuts counter Touch down speed
UTILITIES	 Power 100Vac to 230Vac / 50W Vacuum: 60% Air: 70psiVacuum: 60% Dimensions: 450x700x500mm (18"x28"x20") Weight: 70kgr